



January 12, 2012

PCN Number: 1201

PCN Change Level: Major

Subject: Product Conversion to Copper Wire (palladium coated copper wire)

Dear Customer,

This notice is to inform you that Microsemi SoC Products Group has successfully completed qualification of copper bond wire and plans to ship selected products assembled by Amkor Philippines in PQ208 (MQFP208) packages beginning April 2012. Conversion to palladium coated copper wire (PCC wired) is aligned with the current industry trend. Copper wire is used in high volume production by our assembly vendors and has demonstrated better electrical and mechanical property than gold wire. Amkor has extensive experience in copper bond wire assembly. There is no change to the PQ208 package moisture performance, and it still meets MSL 3 as per JESD22-A113. Products built with copper bond wire will have no change to product functionality, performance, quality, reliability, or product datasheet.

Copper wire conversion qualification has been completed for A3P250 and smaller ProASIC<sup>®</sup>3 devices in PQ208/PQG208 at Amkor Philippines per JEDEC standards. Shipment will begin April 9, 2012. However, mixed shipment could continue until products built with gold wire are depleted from inventory.

Microsemi SoC Products Group intends to start shipping additional products with copper wires in the schedule shown in Table 1 as qualifications are completed.

**Table 1 • Intended Schedule of Shipment**

<b>Device/Package</b>	<b>Schedule</b>
A3P250 and smaller ProASIC3 devices in PQ208/PQG208	April 9, 2012
A3P250 and smaller ProASIC3 devices in FG256/FGG256	End of CY Q2, 2012
ProASIC3/IGLOO <sup>®</sup> devices in VQ100/VQG100	End of CY Q3, 2012
ProASIC3/IGLOO devices in FG144/FGG144	End of CY Q3, 2012

The qualification is in progress for VQ/VQG100, FG/FGG256 and FG144/FGG144. There is no expected change to the moisture performance of these packages.



Affected parts numbers that will convert over on April 9, 2012 are listed in Table 2 (for a list of remaining affected part numbers, refer to [CN 1110](#)).

Feel free to contact Microsemi SoC Products Group Technical Support at [soc\\_tech@microsemi.com](mailto:soc_tech@microsemi.com) if you require any further information.

Regards,

Microsemi Corporation

**Table 2 • Affected Part Numbers**

A3P250-PQ208	A3P250L-1PQG208	M1A3P250-2PQG208I
A3P250-PQG208	A3P250L-PQ208I	M1A3P250-2PQG208I
A3P250-1PQ208	A3P250L-PQG208I	A3P125-PQ208
A3P250-1PQG208	A3P250L-1PQ208I	A3P125-PQG208
A3P250-2PQ208	A3P250L-1PQG208I	A3P125-1PQ208
A3P250-2PQG208	M1A3P250-PQ208	A3P125-1PQG208
A3P250-PQ208I	M1A3P250-PQG208	A3P125-2PQ208
A3P250-PQG208I	M1A3P250-1PQ208	A3P125-2PQG208
A3P250-1PQ208I	M1A3P250-1PQG208	A3P125-PQ208I
A3P250-1PQG208I	M1A3P250-2PQ208	A3P125-PQG208I
A3P250-2PQ208I	M1A3P250-2PQG208	A3P125-1PQ208I
A3P250-2PQG208I	M1A3P250-PQ208I	A3P125-1PQG208I
A3P250L-PQ208	M1A3P250-PQG208I	A3P125-2PQ208I
A3P250L-PQG208	M1A3P250-1PQ208I	A3P125-2PQG208I
A3P250L-1PQ208	M1A3P250-1PQG208I	